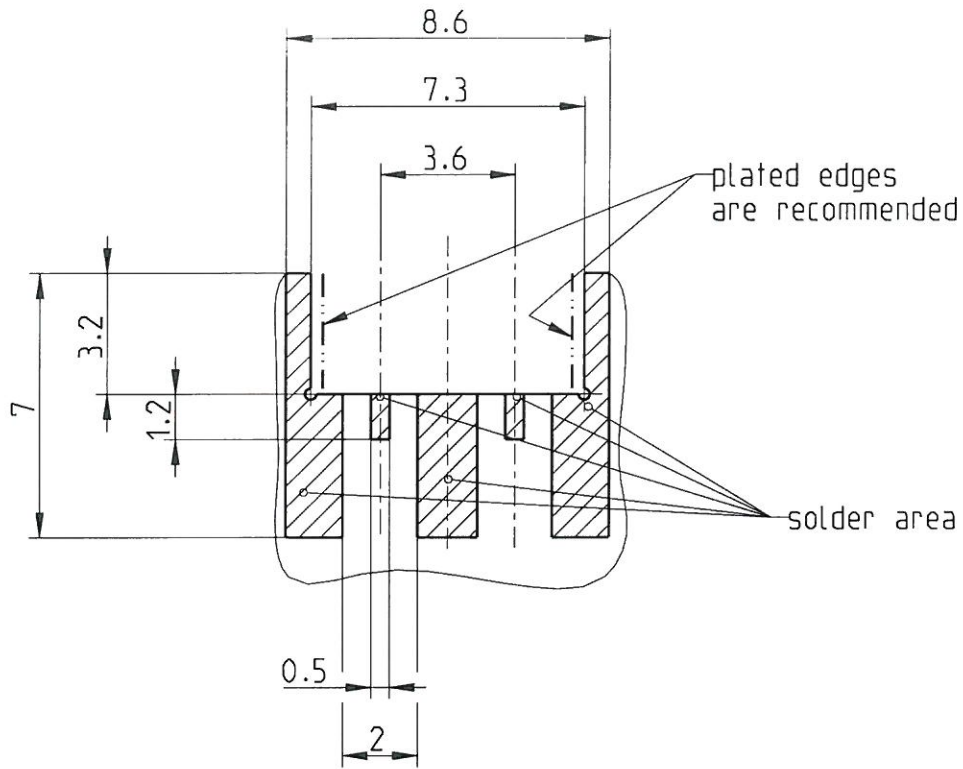


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Leiterplatten-Layout
PCB layout
B 339f



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A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector. Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector. In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

Formulat: T.C.FB.05.PC.A4_Einzelteil
Plat: i:\poe-conf\gabin\...
Datei: AC_ENGZELL.L08.RH
Version: 1.2

DIMENSIONS
in mm



ISO-Projektion
Methode E

Rosenberger Hochfrequenztechnik 84526 Tittmoning Pro/ENGINEER				general tolerance ISO 2768 RN 006-01 m-H dimensions <0.5 and symmetry		scale: 5:1 weight(g): surfacem(m ²):	
				date drawn 28.06.2010 T_Stadler check. 21.9.10 [signature] appr. 22.09.10 [signature]		title: Leiterplatten-Layout PCB layout	
				dimensioning incl. finish		drawing-no.: MB_339F	
a00 10-s632 C_Vitzthum 21.09.2010 100 10-v368 T_Stadler 28.06.2010				distribu- FE AZ QSM RMT . tion to: X		sheet: 1 of: 1	
rev. change-no name date				remarks:			